

## REMARKS

Claims 25 – 27, 30 – 32, 34 and 38 - 44 are now pending in the application. The Examiner is respectfully requested to reconsider and withdrawal the outstanding rejections in view of the amendments and remarks set forth herein.

### Election Requirement

Claims 27-29 and 31-37 stand withdrawn from further consideration pursuant to 37 CFR 1.142(b). Although Applicant does not agree with the Examiner, to expedite prosecution, Applicant elects to cancel claims 28, 29, 33 and 35-37. Claims 27, 30-32 and 34 are amended.

The office action states “how can a light path be formed to the active surface 12a of said semiconductor element 12?”. Referring to Fig. 4, a semiconductor element 12 positioned on an end portion 1a of a first substrate 1. The semiconductor element 12 is spaced apart from an edge of a second substrate 2 so as to form a gap between the semiconductor element 12 and the second substrate 2. A light path is formed from the light source 15, through the gap, ***into and then inside the first substrate 1***, and to an active surface 12a of the semiconductor element 12. As such, the light path is defined without regard to the location of the light shielding member 47. Thereafter, the light shielding member 47 is positioned over the semiconductor element 12 and extends at least partially into the light path. By extending into the light path, the light shielding member disrupts the light path and prevents light from reaching the active surface of the semiconductor element 12. Please note that the defined light path contemplates light reaching the semiconductor element 12 from the direction of the first substrate 1. That

is, at the side of the semiconductor element 12 that is opposite the light shielding member 47. The light shielding member 47 protects the semiconductor element 12 not only by covering it, but also by extending into the light path (i.e., it extends into the gap). This prevents light from propagating through the substrate 1 to reach the side of the semiconductor element 12 opposite the light shielding member 47.

#### **CLAIM OBJECTIONS**

Claim 30 stands objected to under 37 CFR 1.75(c). Claim 30 is amended to delete the term "second". Accordingly, reconsideration and withdraw of this rejection is respectfully requested.

#### **REJECTION UNDER 35 U.S.C. § 103**

Claims 25 and 26 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over Kawaguchi et al. (EP 0402 106 A2). This rejection is respectfully traversed.

Referring to Fig. 4, Claim 25 calls for a semiconductor element 12 mounted on an end portion 1a of a first substrate 1 spaced apart from an edge of a second substrate 2 so as to form a gap between the edge of the second substrate 2 and the semiconductor element 12. Claim 25 also calls for a light shielding member 47 positioned over the semiconductor element 12 and extending into the gap between the edge of the second substrate 2 and the semiconductor device 12. The light shielding member 47 extends toward the first substrate 1. In contrast, Kawaguchi discloses light shielding members (e.g., light shielding member 38) that extend parallel to or away from a first substrate 32.

Inasmuch as Kawaguchi fails to teach a light shielding member extending toward a first substrate, Kawaguchi does not render the claimed invention obvious. Accordingly, reconsideration and withdrawal of this rejection are respectfully requested.

Claim 26 depends from claim 25 and should be allowable for at least the same reasons as set forth above.

#### **NEW CLAIMS**

New claims 38-44 are added. Claims 38 and 40 call for the light shielding member to comprise an adhesive tape. Claims 39 and 41 call for the adhesive tape to be elastic. Claim 42 calls for the light shielding member of claim 25 to be connected to the first substrate. Claim 43 calls for a polarizing plate extending under an entire active surface of a semiconductor element. Claim 44 calls for the polarizing plate to extend over all of the bump electrodes of the semiconductor element. Favorable consideration of these new claims is respectfully requested.

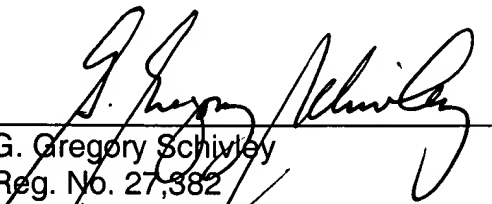
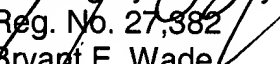
#### **CONCLUSION**

It is believed that all of the stated grounds of rejection have been properly traversed, accommodated, or rendered moot. Applicant therefore respectfully requests that the Examiner reconsider and withdraw all presently outstanding rejections. It is believed that a full and complete response has been made to the outstanding Office Action, and as such, the present application is in condition for allowance. Thus, prompt and favorable consideration of this amendment is respectfully requested. If the

Examiner believes that personal communication will expedite prosecution of this application, the Examiner is invited to telephone the undersigned at (248) 641-1600.

Respectfully submitted,

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